

SOT780-1

plastic thermal enhanced thin quad flat package; 52 leads;
body 10 x 10 x 1 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP52
Package type industry code	HTQFP52
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	4-9-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
n ₂	actual quantity of termination	-	-	52	-	

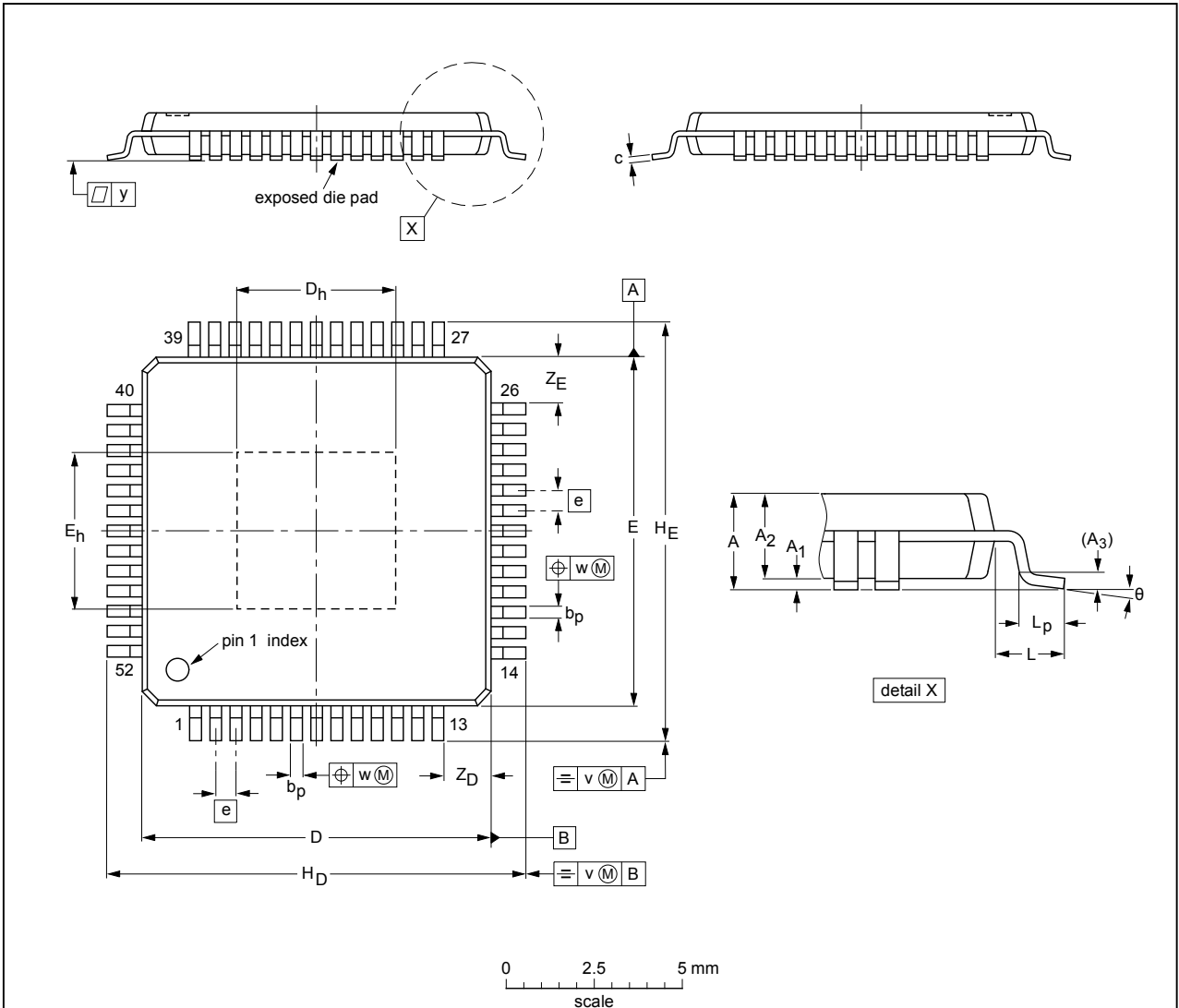


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2. Package outline

HTQFP52: plastic thermal enhanced thin quad flat package;
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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.2	0.15 0.05	1.05 0.95	0.25	0.38 0.22	0.20 0.09	10.1 9.9	4.6 4.4	10.1 9.9	4.6 4.4	0.65	12.15 11.85	12.15 11.85	1	0.75 0.45	0.2	0.13	0.1	1.3 0.9	1.3 0.9	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT780-1		MS-026				02-09-04

Fig. 1. Package outline HTQFP52 (SOT780-1)

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3. Legal information

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